

Discription

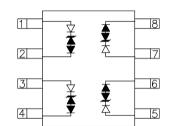
The HSLVU2.84TBT protects sensitive semiconductor components from damage or upset due to electrostatic discharge (ESD) and other voltage induced transient events. Excellent clamping capability, low leakage, low capacitance, and fast response time provide best in class protection on designs that are exposed to ESD.

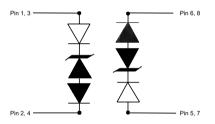
Features

- 400W peak pulse power (8/20µs)
- Protects two line pairs (four lines)
- Ultra low leakage: nA level
- Low operating voltage: 2.8V
- Very low capacitance: 2pF
- Ultra low clamping voltage
- JEDEC SO-8 package
- Complies with following standards:
 - IEC 61000-4-2 (ESD) immunity test
 Air discharge: ±30kV
 - Contact discharge: ±30kV
 - IEC61000-4-5 (Lightning) 30A (8/20µs)
- RoHS Compliant









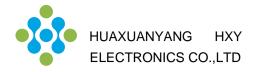
Circuit Diagram

Ordering information

	Product ID	Pack	Qty(PCS)		
Ī	HSLVU2.84TBT	SOP-8(SO-8)	2500		

Absolute Ratings (Tamb=25°C)

Symbol	Parameter	Value	Units
P _{PP}	Peak Pulse Power (t _P = 8/20µs)	400	W
TL	Maximum lead temperature for soldering during 10s	260	°C
T _{stg}	Storage Temperature Range	-55 to +150	°C
T _{op}	Operating Temperature Range	-40 to +125	°C
Tj	Maximum junction temperature	150	°C
	IEC61000-4-2 (ESD) air discharge contact discharge		ΚV

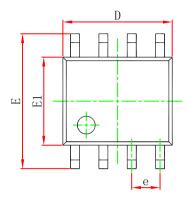


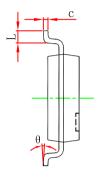
Electrical Characteristics (T_A=25°C unless otherwise specified)

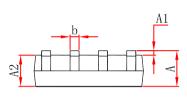
Parameter	Symbol	Min	Тур	Мах	Unit	Test Condition
Reverse Working Voltage	VRWM			2.8	V	
	VBR	3.0			V	Ιτ = 2μΑ
Breakdown Voltage	Vsb	3.0			V	ISB= 50mA
Reverse Leakage Current	I _R		0.001	1	μA	VRWM = 2.8V
Clamping Voltage	Vc			8.5	V	IPP = 5A (8 x 20µs pulse)
Clamping Voltage	Vc			18	V	IPP = 20A (8 x 20µs pulse)
Junction Capacitance	Cl		2	3	pF	VR = 0V, f = 1MHz



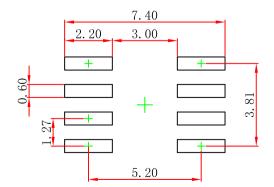
SOP-8(SO-8) Package Outline Dimensions







Symbol	Dimensions In	Millimeters	Dimensions In Inches		
Symbol	Min	Max	Min	Max	
А	1.350	1.750	0.053	0.069	
A1	0.100	0.250	0.004	0.010	
A2	1.350	1.550	0.053	0.061	
b	0.330	0.510	0.013	0.020	
с	0.170	0.250	0.007	0.010	
D	4.800	5.000	0.189	0.197	
e	1.270 (BSC)		0.050 (BSC)		
E	5.800	6.200	0.228	0.244	
E1	3.800	4.000	0.150	0.157	
L	0.400	1.270	0.016	0.050	
θ	0 °	8°	0 °	8°	



Note: 1.Controlling dimension:in millimeters.

2.General tolerance:± 0.05mm.
 3.The pad layout is for reference purposes only.



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